

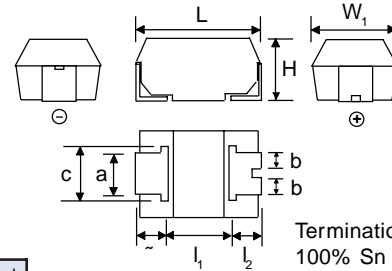


### MAXIMUM LEAKAGE CURRENT @25°C (µA)

Capacitance (µF)	6.3Vdc	10Vdc	16Vdc	20Vdc	25Vdc	35Vdc
10	0.7	1.0	1.6	2.0	2.5	3.5
15	1.0	1.5	2.4	3.0	3.8	5.3
22	1.4	2.2	3.5	4.4	5.5	7.7
33	2.1	3.3	5.3	6.6	8.3	-
47	3.0	4.7	7.5	9.4	-	-
68	4.3	6.8	11	-	-	-
100	6.3	10	16	-	-	-
150	9.5	15	-	-	-	-
220	14	22	-	-	-	-
330	20.8	33	-	-	-	-
470	32.9	-	-	-	-	-

### CASE DIMENSIONS (mm)

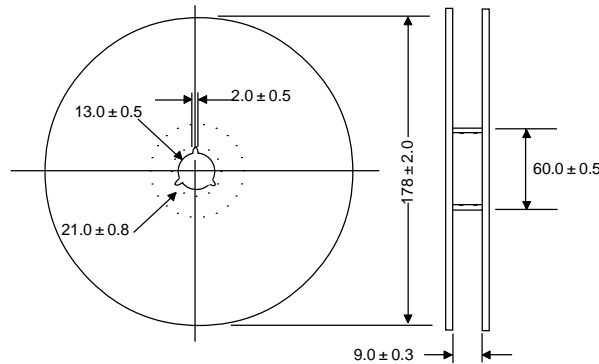
Case Code	L ± 0.2	W ± 0.2	H ± 0.2	l <sub>1</sub> ± 0.2	l <sub>2</sub> ± 0.2	a ± 0.2	b ± 0.2	c ± 0.1
B	3.4	2.6	1.9	1.4	0.8	2.0	0.7	2.2
C	5.8	3.2	2.5	2.4	1.3	2.2	0.7	2.4
D	7.3	4.3 ± 0.3	2.8	3.8	1.3	3.1	1.2	3.3



Terminations:  
100% Sn (Lead-Free)  
Standard

### TAPING SPECIFICATIONS (mm)

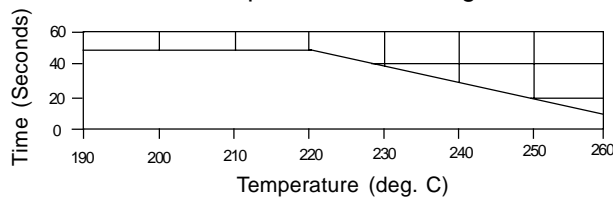
Case Size	A ±0.1	B ±0.1	C ±0.3	D ±0.1	E ±0.1	F ±0.1	G ±0.1	H ±0.1	J ±0.1	K max.	t max.	Reel Qty
B	3.1	3.9	8.0	3.5	1.75	4.0	2.0	4.0	1.5	2.5	0.2	2000
C	3.7	6.3	12.0	5.5	1.75	8.0	2.0	4.0	1.5	3.0	0.3	500
D	4.8	7.7	12.0	5.5	1.75	8.0	2.0	4.0	1.5	3.4	0.3	500



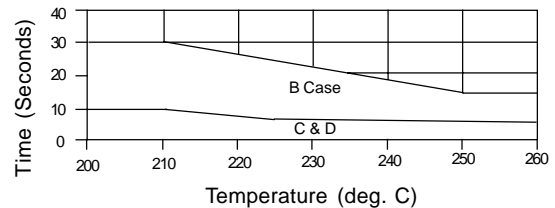
### RECOMMENDED SOLDERING PROFILES

Note: To avoid thermal shock a preheating stage, 130°C ~ 160°C for 1 minute, should be incorporated into the soldering process

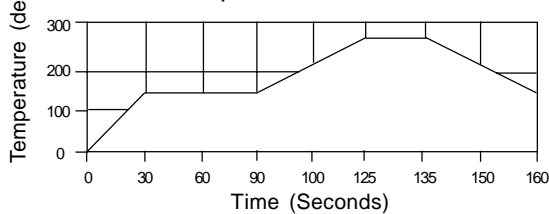
Reflow Soldering - Permitted Temperature/Time Range



Flow Soldering - Permitted Temperature/Time Range



Reflow Soldering - Recommended Profile Maximum Temperature/Time: 260°C/10 Sec.



Flow Soldering - Recommended Profile Maximum Temperature/Time: 245°C/5 Sec.

